



Material Content Data Sheet



Sales Product Name		TLE7469G V52		Issued		28. August 2013			
MA#		MA000616592							
Package		PG-DSO-12-11		Weight*		402.01 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	3.559	0.89	0.89	8852	8852	
leadframe	non noble metal	iron	7439-89-6	0.230	0.06		573		
	inorganic material	phosphorus	7723-14-0	0.069	0.02		172		
	non noble metal	copper	7440-50-8	230.106	57.23	57.31	572396	573141	
wire	non noble metal	aluminium	7429-90-5	0.155	0.04	0.04	385	385	
encapsulation	organic material	carbon black	1333-86-4	0.316	0.08		787		
	plastics	epoxy resin	-	14.547	3.62		36185		
	inorganic material	silicondioxide	60676-86-0	143.252	35.63	39.33	356344	393316	
leadfinish	non noble metal	tin	7440-31-5	4.235	1.05	1.05	10535	10535	
plating	inorganic material	phosphorus	7723-14-0	0.002	0.00		4		
	non noble metal	nickel	7440-02-0	0.630	0.16	0.16	1567	1571	
solder	noble metal	silver	7440-22-4	0.123	0.03		305		
	non noble metal	tin	7440-31-5	0.098	0.02		244		
	non noble metal	lead	7439-92-1	4.684	1.17	1.22	11651	12200	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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